

Jan. 24. 2006 12:44PM

RECEIVED No. 0633 P. 1  
CENTRAL FAX CENTER

JAN 24 2006

CERTIFICATE OF FACSIMILE TRANSMISSION

ATTORNEY DOCKET: CPAC 1029-5

I hereby certify that this correspondence is being sent by facsimile to:  
Mail Stop Issue Foc, Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450 at  
(571) 273-8300 on 24 January 2006.

Signed:

  
Paula Faulk Hurley

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Marcos Karnezos

Attorney Docket No.: CPAC 1029-5

Application No.: 10/681,583

Examiner: Alonso Chambliss

Filed: 08 October 2003

Group: 2814

Title: Semiconductor multi-package module  
having inverted second package stacked over  
die-down flip-chip ball grid array (BGA)  
package

Confirmation No.: 6814

Customer No. 22470

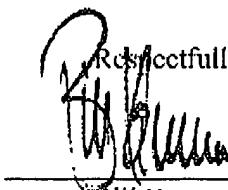
Box Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

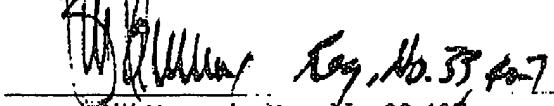
**SUBMISSION OF PRIOR ART AFTER NOTICE OF ALLOWANCE**

Sir:

Applicants submit the below-listed document to be placed in the file:

- Pedron, Jr.; U. S. Patent No. 6,818,980 issued 16 November 2004 for "Stacked Semiconductor Package and Method of Manufacturing Same".

  
Respectfully submitted,

  
Bill Kennedy, Reg. No. 33,407

Date: 24 January 2006

HAYNES BEFFEL & WOLFELD LLP  
P.O. Box 366  
Half Moon Bay, CA 94019  
(650) 712-0340 (telephone)  
(650) 712-0263 (facsimile)

1 of 2